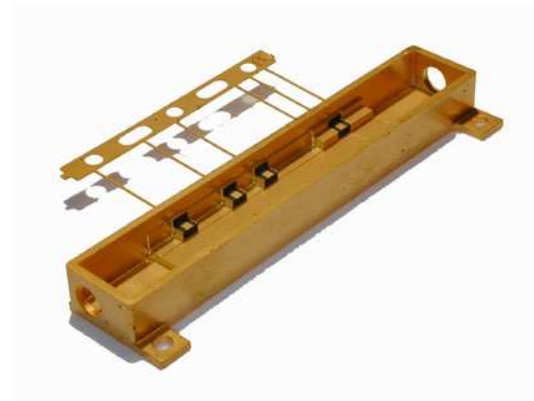
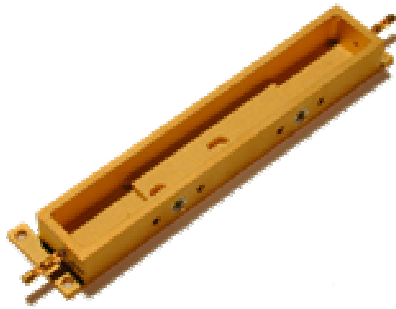




Description

Egide's modulator packages are manufactured using either glass-to-metal seal (GTMS) or ceramic to metal seal (CTMS). They are designed to incorporate substrates like LiNbO₃ or other specialty materials. We are able to custom design the shape and size to meet your needs. Egide's integration capabilities such as microwave connectors, tubes, and optics, combined with a flexible mechanical design, will optimize your package's performance and your application's needs.



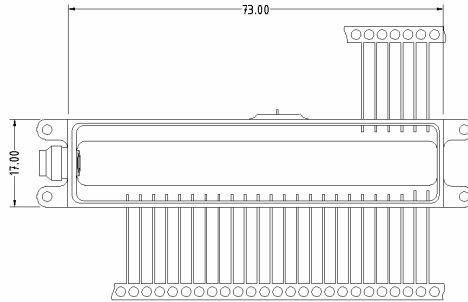
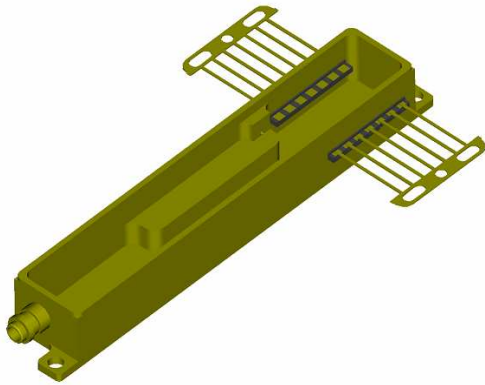
Features

- Hermeticity: 1×10^{-8} cc/s atm He
- Thin film interconnect
- Integration of other components using brazing and welding technologies (TEC, sapphire, selfoc, ball lenses, tubes, ...)
- Microwave connector assembly (SMA, GPO, GPPO, ...)
- GTMS or CTMS feedthru design
- Customized design with rapid turn around times

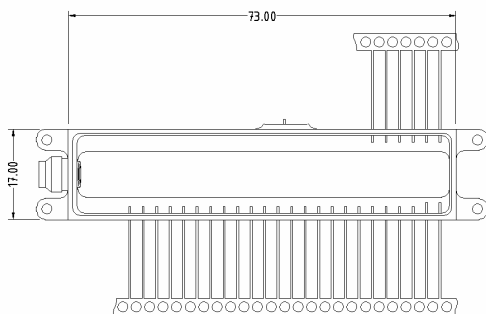
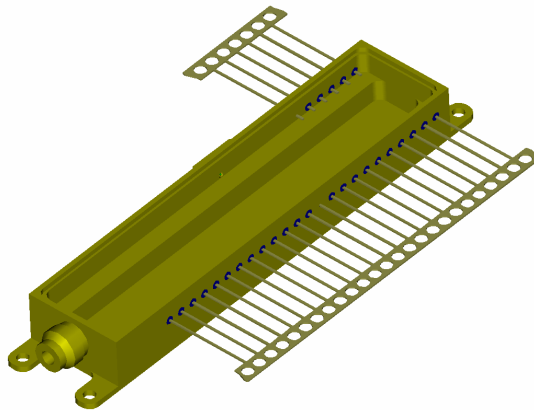
Contact : sales@egideusa.com - sales@egide.fr
www.egideusa.com - www.egide.fr



Package outline (examples)



Dimensions in mm



Dimensions in mm

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